Thermal transfer compound and thermal interface film

Silicon thermal transfer compound

Thermal transfer compound used to reduce the thermal transmission resistance between semiconductor and heatsink.

art. no.	container	delivery quantity [g]
WLP 004	box	4
WLP 035	box	35
WLP 500	box	500
WLP 300 S	cartridge	300
WLP 500 S	cartridge	500

Silicone-free thermal transfer compound

Thermal transfer compound used to reduce the thermal transmission resistance between semiconductor and heatsink.

art. no.	container	delivery quantity [ml]
WLPF 05	syringe	2
WLPF 10	syringe	5
WLPF 20	syringe	10
WLPF 50	syringe	20

Technical data

	WLP	**WLPF**
composition	silicone oil, inorganic filling material	Silicone free synthetic liquid. Metal oxide filling.
consistance	pastey	pastey
colour	white	white-grey
tightness	1.1 g/cm^3	ca. 2 g/cm^3
thermal conductivity	0.61	>0.7
specific electrical resistance	>10^{12} Ω/cm	>10^{12} Ω/cm
flashpoint	none (DIN 53213)	of the basic oil >280 °C (ISO 2592)
drop point	>260 °C	–
thermal resistance	no bleeding at (4 h / 200°C)	<1 % (96 h / 200 °C)
temperature range	-70 °C ... +250 °C	-40 °C ... +150 °C
acid number	< 0.01 mg KOH/g	–
solubility in water	insoluble	insoluble

Mica wafers → **E 11**
Kapton insulator washers → **E 8**
Mounting pads → **E 39**
Mounting parts for heatsinks → **E 42 – 43**
Silicone wafers → **E 2 – 4**
Thermal conductive foil → **E 5**
Thermal. conductive silicone foam foil → **E 6**
Insulator caps → **E 43**